

Product Summary

| Device | $V_{(BR)DSS}$ | $R_{DS(ON) \max}$ | $I_{D \max}$ $T_A = +25^\circ\text{C}$ |
|-----------|---------------|---------------------------------------|---|
| N-Channel | 30V | 20m Ω @ $V_{GS} = 10\text{V}$ | 7.3A |
| | | 24m Ω @ $V_{GS} = 4.5\text{V}$ | 6.7A |

Description

This MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC Motor Control
- DC-AC Inverters

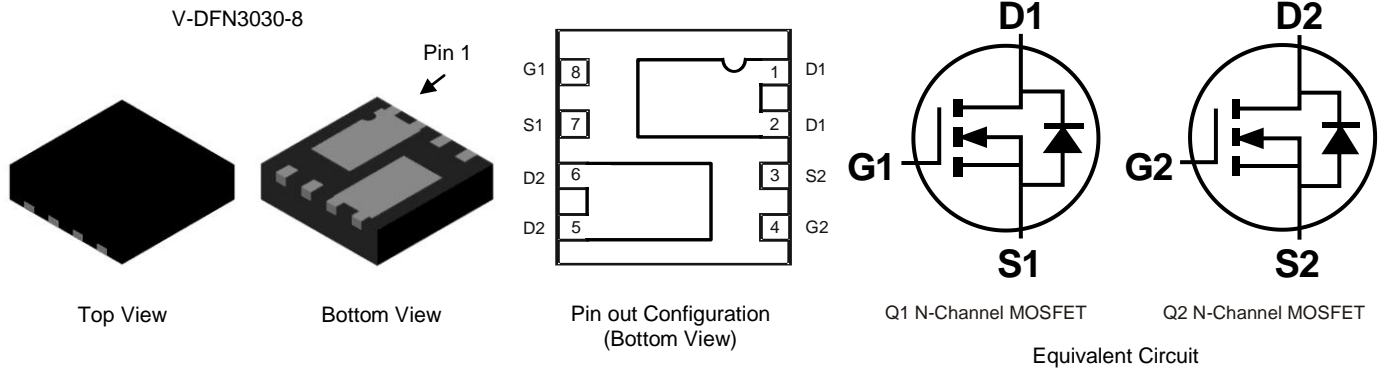
Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: V-DFN3030-8
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Weight: 0.02 grams (Approximate)

NEW PRODUCT

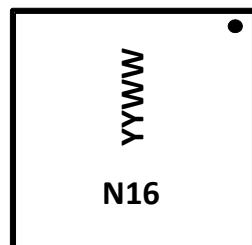


Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------|-------------|-------------------|
| DMN3016LDN-7 | V-DFN3030-8 | 3000/Tape & Reel |
| DMN3016LDN-13 | V-DFN3030-8 | 10000/Tape & Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



N16 = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Last Digit of Year (ex: 13 for 2013)
 WW = Week Code (01 ~ 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | | Symbol | Value | Units |
|---|--------------|--|------------------|------------|-------|
| Drain-Source Voltage | | | V _{DSS} | 30 | V |
| Gate-Source Voltage | | | V _{GSS} | ±20 | V |
| Continuous Drain Current (Note 6) V _{GS} = 10V | Steady State | T _A = +25°C T _A = +70°C | I _D | 7.3 5.8 | A |
| | t < 10s | T _A = +25°C T _A = +70°C | I _D | 9.2 7.3 | A |
| Maximum Continuous Body Diode Forward Current (Note 6) | | | I _S | 2.5 | A |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) | | | I _{DM} | 45 | A |
| Avalanche Current (Note 7) L = 0.1mH | | | I _{AS} | 22 | A |
| Avalanche Energy (Note 7) L = 0.1mH | | | E _{AS} | 24 | mJ |

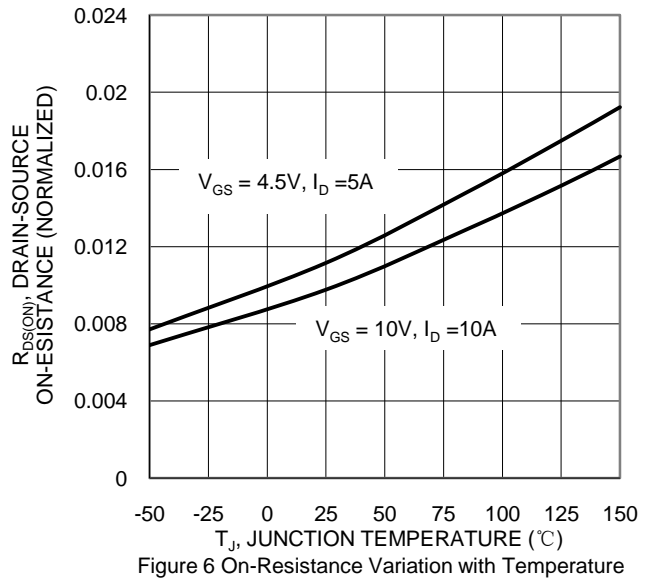
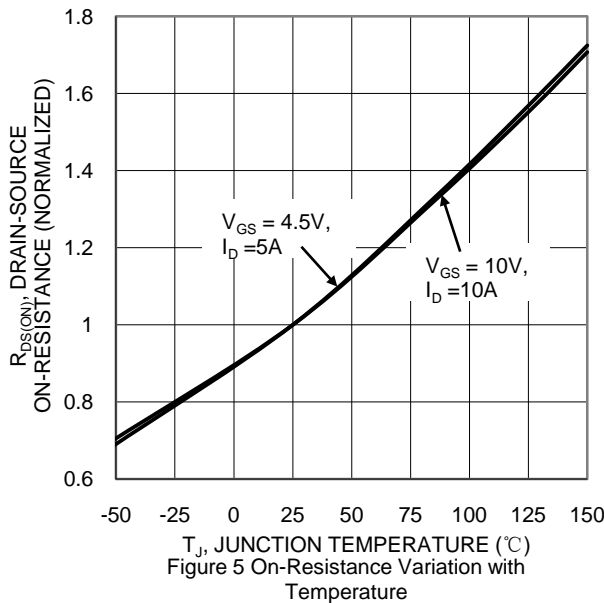
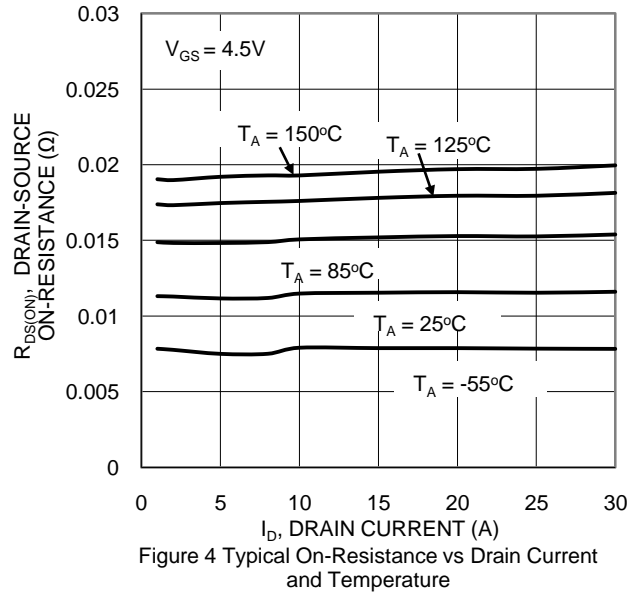
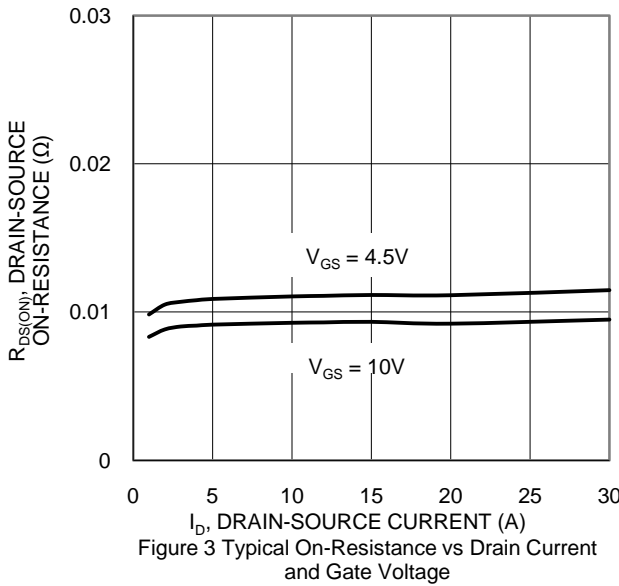
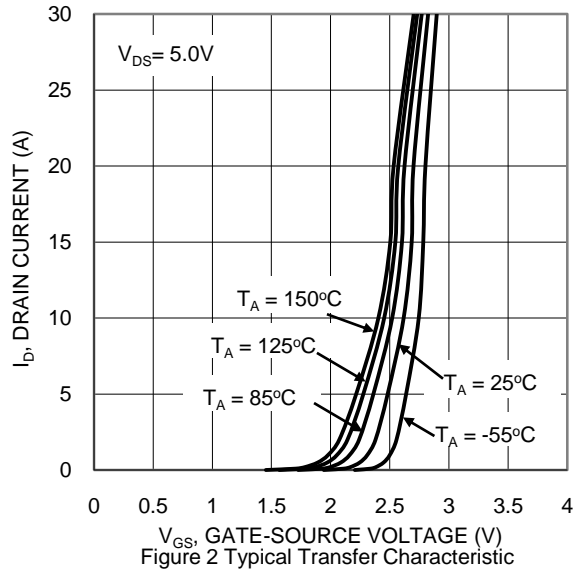
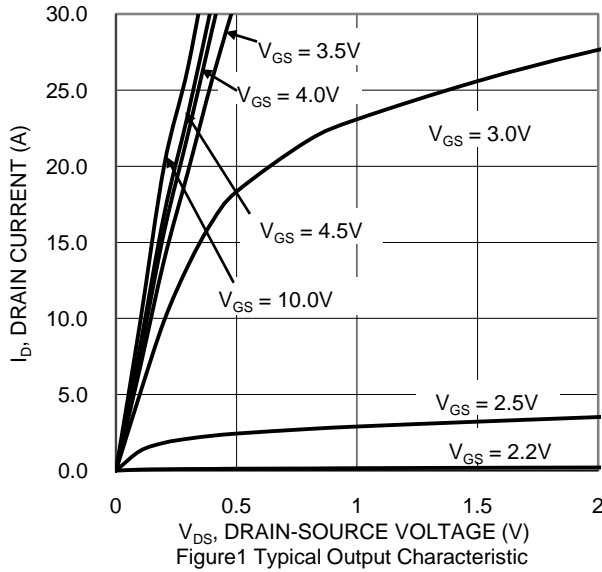
Thermal Characteristics

| Characteristic | | Symbol | Value | Units |
|--|------------------------|-----------------------------------|-------------|-------|
| Total Power Dissipation (Note 5) | T _A = +25°C | P _D | 1.1 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State | R _{θJA} | 119 | °C/W |
| | t < 10s | | 75 | |
| Total Power Dissipation (Note 6) | T _A = +25°C | P _D | 1.6 | W |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State | R _{θJA} | 78 | °C/W |
| | t < 10s | | 49 | |
| Thermal Resistance, Junction to Case (Note 6) | | R _{θJC} | 13.5 | |
| Operating and Storage Temperature Range | | T _J , T _{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--|---------------------|-----|------|------|------|--|
| OFF CHARACTERISTICS (Note 8) | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 30 | - | - | V | V _{GS} = 0V, I _D = 250µA |
| Zero Gate Voltage Drain Current | I _{DSS} | - | - | 1 | µA | V _{DS} = 30V, V _{GS} = 0V |
| Gate-Source Leakage | I _{GSS} | - | - | ±100 | nA | V _{GS} = ±20V, V _{DS} = 0V |
| ON CHARACTERISTICS (Note 8) | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | 1.4 | - | 2.0 | V | V _{DS} = V _{GS} , I _D = 250µA |
| Static Drain-Source On-Resistance | R _{DS(ON)} | - | - | 20 | mΩ | V _{GS} = 10V, I _D = 11A |
| | | - | - | 24 | | V _{GS} = 4.5V, I _D = 9A |
| Diode Forward Voltage | V _{SD} | - | 0.70 | 1.0 | V | V _{GS} = 0V, I _S = 1A |
| DYNAMIC CHARACTERISTICS (Note 9) | | | | | | |
| Input Capacitance | C _{iss} | - | 1415 | - | pF | V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz |
| Output Capacitance | C _{oss} | - | 119 | - | | |
| Reverse Transfer Capacitance | C _{rss} | - | 82 | - | | |
| Gate Resistance | R _g | - | 2.6 | - | Ω | V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz |
| Total Gate Charge (V _{GS} = 4.5V) | Q _g | - | 11.3 | - | nC | V _{DS} = 15V, I _D = 12A |
| Total Gate Charge (V _{GS} = 10V) | Q _g | - | 25.1 | - | | |
| Gate-Source Charge | Q _{gs} | - | 3.5 | - | | |
| Gate-Drain Charge | Q _{gd} | - | 3.6 | - | | |
| Turn-On Delay Time | t _{D(ON)} | - | 4.8 | - | ns | V _{DD} = 15V, V _{GS} = 10V, R _L = 1.25Ω, R _G = 3Ω |
| Turn-On Rise Time | t _R | - | 16.5 | - | | |
| Turn-Off Delay Time | t _{D(OFF)} | - | 26.1 | - | | |
| Turn-Off Fall Time | t _F | - | 5.6 | - | | |
| Reverse Recovery Time | t _{RR} | - | 12.3 | - | ns | I _F = 12A, di/dt = 500A/µs |
| Reverse Recovery Charge | Q _{rr} | - | 10.4 | - | nC | |

- Notes:
- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1in. square copper plate.
 - I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = +25°C.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.



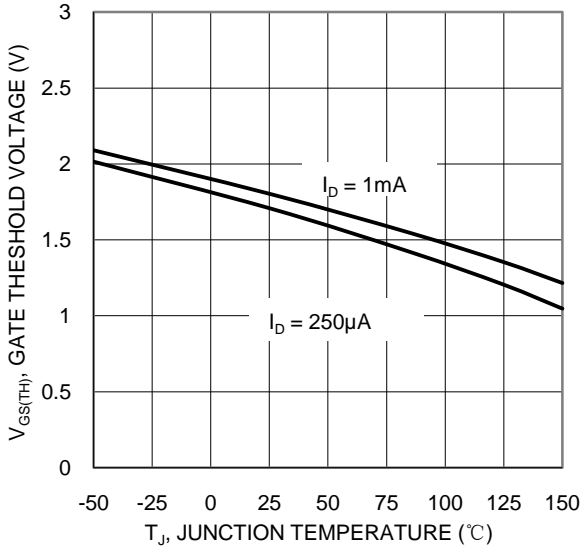


Figure 7 Gate Threshold Variation vs Junction Temperature

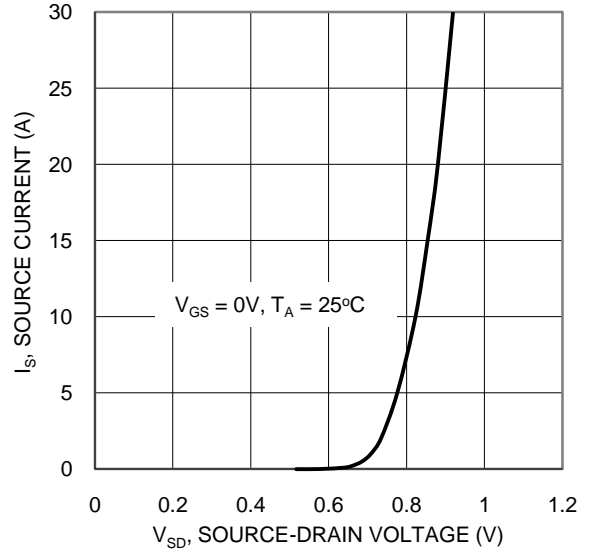


Figure 8 Diode Forward Voltage vs Current

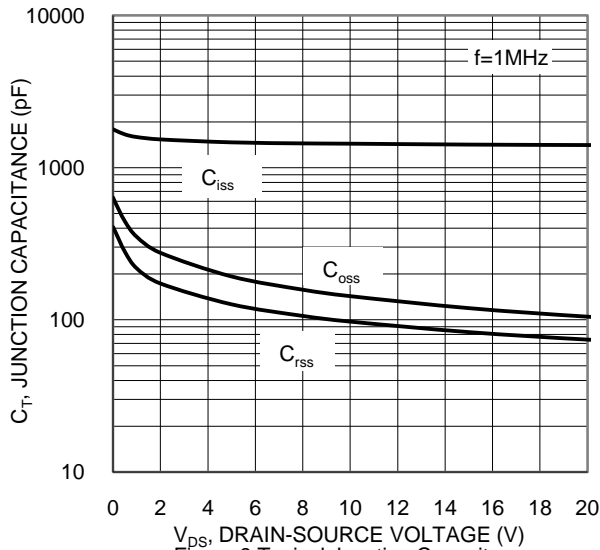


Figure 9 Typical Junction Capacitance

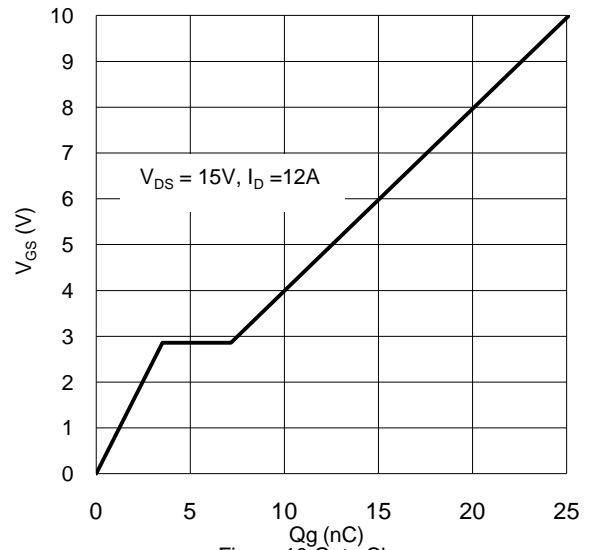


Figure 10 Gate Charge

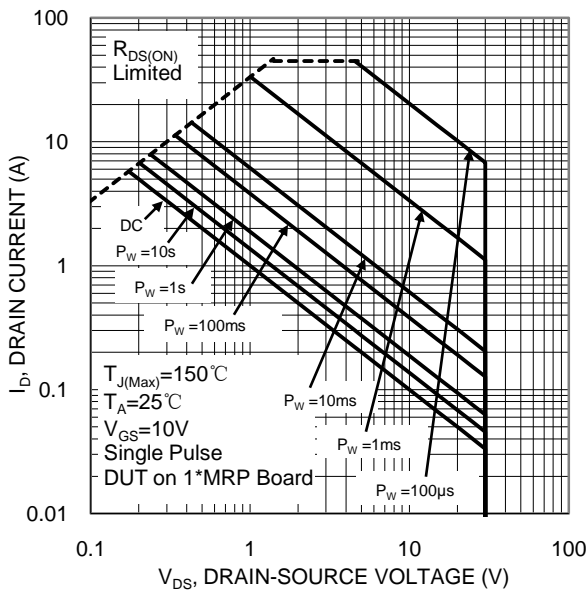


Figure 11 SOA, Safe Operation Area

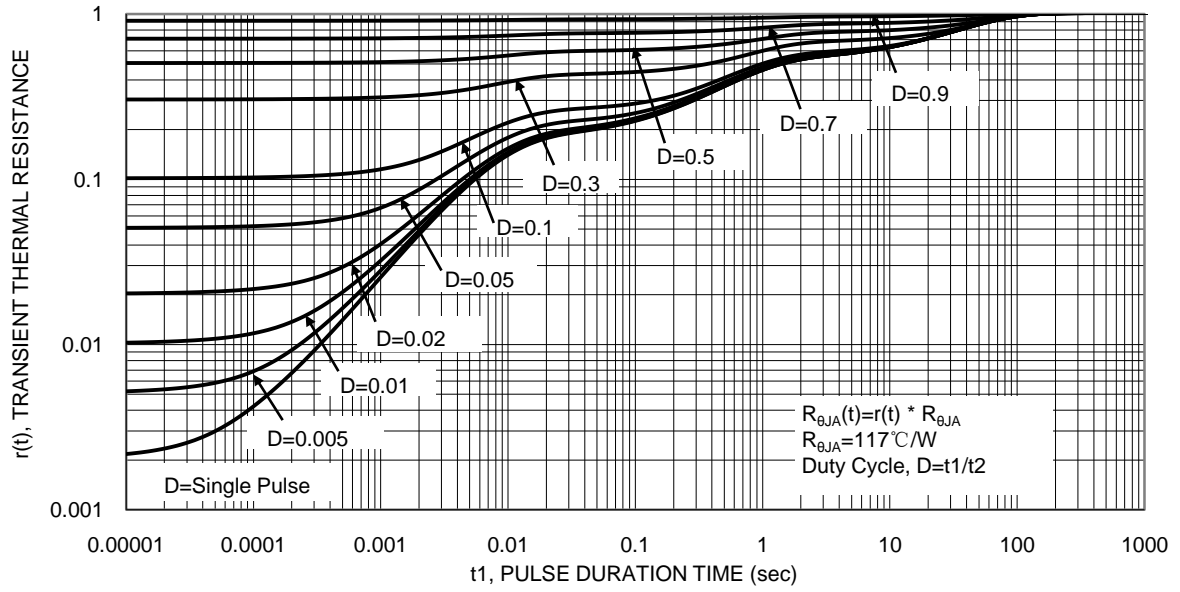
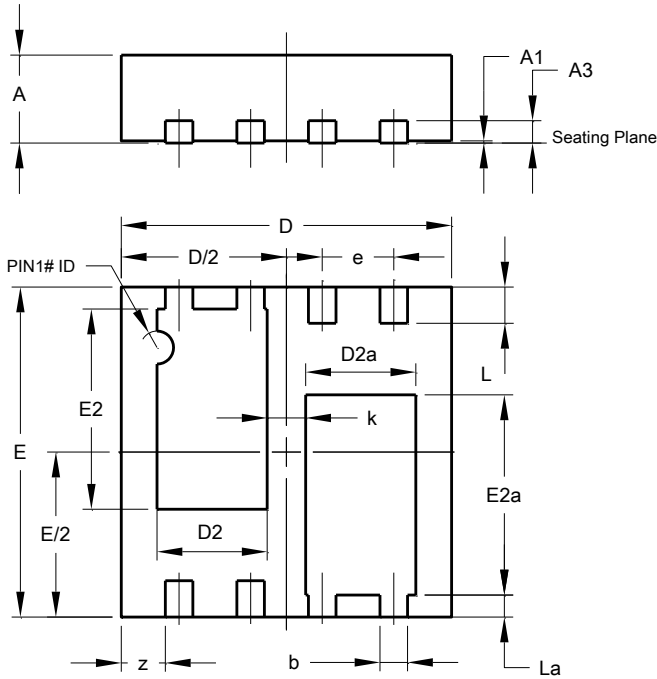


Figure 12 Transient Thermal Resistance

Package Outline Dimensions

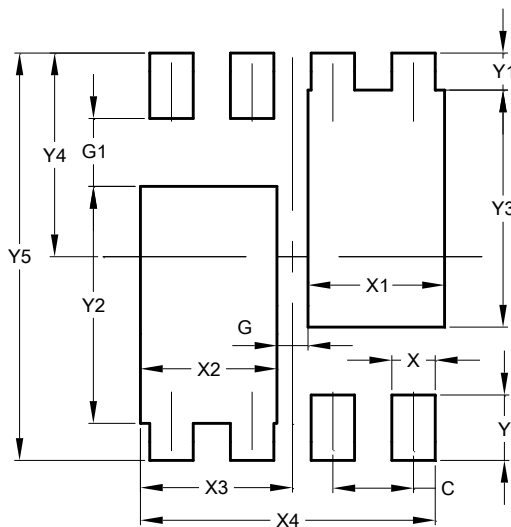
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



| V-DFN3030-8 (Type J) | | | |
|-------------------------|-----------|-------|------|
| Dim | Min | Max | Typ |
| A | 0.77 | 0.83 | 0.80 |
| A1 | 0.00 | 0.05 | 0.02 |
| A3 | 0.203 BSC | | |
| b | 0.20 | 0.30 | 0.25 |
| D | 2.95 | 3.050 | 3.00 |
| D2 | 0.90 | 1.10 | 1.00 |
| D2a | 0.90 | 1.10 | 1.00 |
| E | 2.95 | 3.050 | 3.00 |
| E2 | 1.72 | 1.92 | 1.82 |
| E2a | 1.72 | 1.92 | 1.82 |
| e | 0.65BSC | | |
| L | 0.27 | 0.38 | 0.33 |
| La | 0.15 | 0.25 | 0.20 |
| k | 0.35 TYP | | |
| z | 0.40 BSC | | |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



| Dimensions | Value (in mm) |
|------------|------------------|
| C | 0.650 |
| G | 0.250 |
| G1 | 0.550 |
| X | 0.350 |
| X1 | 1.100 |
| X2 | 1.100 |
| X3 | 1.225 |
| X4 | 2.375 |
| Y | 0.530 |
| Y1 | 0.300 |
| Y2 | 1.920 |
| Y3 | 1.920 |
| Y4 | 1.650 |
| Y5 | 3.300 |

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